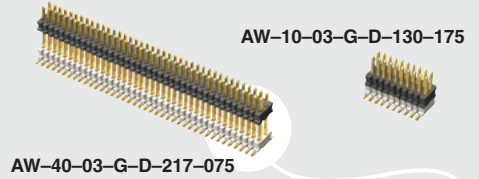
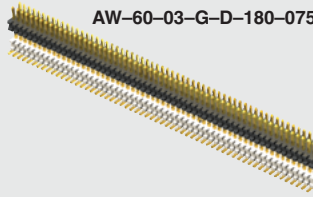


FLEX STACK



(0.80 mm) .0315"

AW SERIES

SMT MICRO BOARD STACKER

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?AW

Insulator Material:

Top: Black LCP
Bottom: Natural LCP

Terminal Material:

Phosphor Bronze

Plating:

Au over 50 μ" (1.27 μm) Ni

Operating Temp Range:

-55 °C to +125 °C

RoHS Compliant:

Yes

PROCESSING

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max (05-40)

(0.15 mm) .006" max (41-90)*

*(.004" stencil solution may be available; contact

IPG@samtec.com)

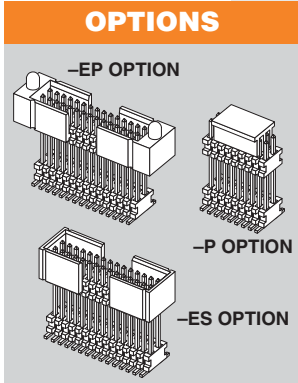
RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



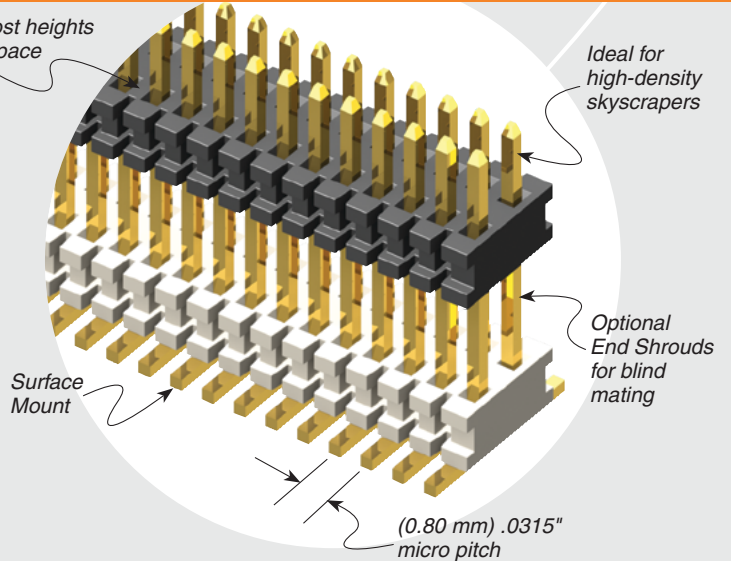
FILE NO. E111594

Mates with:
CLE



Choice of post heights and board space

Ideal for high-density skyscrapers



AW	NO. PINS PER ROW	03	PLATING OPTION	D	STACKER HEIGHT	POST HEIGHT	OPTION
	05 thru 90		-G = 10 μ" (0.25 μm) Gold		- "XXX" = Stacker Height (in inches) (3.09 mm) .122" to (5.84 mm) .230"	- "XXX" = Post Height (in inches) (1.91 mm) .075" minimum	-ES = End Shroud (11 pins/row min. (-075 Post Height only)) -EP = End Shroud with Guide Post (075 Post Height only) (11 pins/row min.) -A = Alignment Pin (4 positions min.) (Available for board stacks between (4.06 mm) .160" to (5.84 mm) .230") (Metal or plastic at Samtec discretion.) -P = Pick & Place Pad (8 positions min.) -TR = Tape & Reel (84 positions max.)

Notes:

For added mechanical stability, Samtec recommends mechanical board spacers be used in applications with gold or selective gold plated connectors. Contact ipg@samtec.com for more information.

Some lengths, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM

All parts within this catalog are built to Samtec's specifications.

Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.